

AMENDMENTS TO THE CLAIMS:

Please amend Claims 22 and 25-33 as follows:

1-21. (Cancelled)

22. (Currently Amended) A pod ~~capable of including a substrate~~ attachable to an outside surface of an electromagnetic-shielded chamber which covers a device manufacturing apparatus, the device manufacturing apparatus importing a substrate from said pod, said pod comprising:

walls ~~which form the opening; and~~

a lid for ~~the~~ an opening defined by the walls, the substrate in said pod being imported to the device manufacturing apparatus through the opening; and,

wherein said walls comprise an electromagnetic shield member, which is provided by said walls, at least and a portion of said electromagnetic shield member being provided on said walls so as to contact the electromagnetic-shielded chamber so that said is arranged on a part of said walls which contacts the electromagnetic shield member is grounded through the electromagnetic-shielded chamber.

23. (Previously Presented) A pod according to Claim 22, wherein said lid is arranged in front of said pod.

24. (Previously Presented) A pod according to Claim 22, wherein said lid is arranged in a bottom of said pod.

25. (Currently Amended) A pod according to Claim 22, wherein said electromagnetic shield member comprises wire mesh ~~provided~~ arranged on or within said walls.

26. (Currently Amended) A pod according to Claim 22, wherein said electromagnetic shield member comprises metal coatings ~~provided~~ arranged on said walls.

27. (Currently Amended) A pod according to Claim 22, wherein said electromagnetic shield member comprises electromagnetic-shield materials ~~provided~~ arranged in said walls.

28. (Currently Amended) -An apparatus for manufacturing a device using a substrate, said apparatus comprising:

an electromagnetic-shielded chamber;

~~an importing handling~~ unit which imports the substrate ~~through an opening of into a pod pressed against~~ said electromagnetic-shielded chamber from a pod attached to an outside surface of said electromagnetic chamber; and

a processing unit which ~~processes~~ performs a process using the substrate imported by said ~~importing~~ handling unit;

wherein said electromagnetic shielded chamber has a grounded portion, ~~against~~

~~which the pod is to be pressed, of said electromagnetic-shielded chamber is grounded for~~
contacting the pod.

29. (Currently Amended) An apparatus according to claim 28, wherein said grounded portion is ~~provided~~ arranged around ~~an opening~~ a door of said electromagnetic-shielded chamber through which said ~~importing~~ handling unit imports the substrate.

30. (Currently Amended) An apparatus according to Claim 28, wherein ~~said processing unit has a function of exposing~~ the process performed by said process unit is exposure of the substrate to a pattern.

31. (Currently Amended) An apparatus according to Claim 28, wherein a lid ~~for the opening~~ of the pod is arranged in front of the pod.

32. (Currently Amended) An apparatus according to Claim 28, wherein a lid ~~for the opening~~ of the pod is arranged in a bottom of the pod.

33. (Currently Amended) An apparatus according to Claim 28, wherein walls of the pod comprises an electromagnetic shield member ~~is provided by the walls of the pod.~~

Claims 34 through 37. (cancelled)

38. (Withdrawn) A device manufacturing method comprising a step of transferring a substrate using a pod defined in Claim 22.

39. (Withdrawn) A device manufacturing method comprising a step of processing a substrate using an apparatus defined in Claim 28.

40. (Withdrawn) A method according to Claim 39, wherein in said processing step, the substrate is exposed to a pattern.